ABSTRACT

INTEGRATED CIRCUIT SYSTEM WITH STRESS REDISTRIBUTION LAYER AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit system includes: providing a substrate having a transistor and a metallization layer; forming a metal pad in direct contact with the metallization layer of the substrate; forming a passivation layer in direct contact with the metal pad and covering the substrate; forming a routing trace above the passivation layer in direct contact with the metal pad, and the routing trace is substantially larger than the metal pad, and the routing trace is not electrically insulated by a subsequent layer; and forming a bump connected to the metal pad with the routing trace.
(Fig. 2)